

LTM2987-BGA 144LD 15mm X 15mm X 3.42mm (TABLE OF MATERIAL DECLARATION)							
The LTM2987 is RoHS compliant per EU RoHS Directive 2003/95/EC. It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1859	Barium Compounds	7727-43-7	0.00364	1.96
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.03313	17.82
				Copper Metal	7440-50-8	0.11223	60.37
				Copper Compounds	147-14-8	0.00003	0.02
				Ecotoxic substances	7440-38-2, 7439-92-1	0.00001	0.01
				Phosphorus	7723-14-0	0.00020	0.11
				Palladium	7440-05-3	0.00003	0.02
				Gold metal or alloy	7440-57-5	0.00011	0.06
				Nickel	7440-02-0	0.00231	1.24
				Zinc	7440-66-6	0.00014	0.07
				Continuous Filament Fiber Glass	65997-17-3	0.02605	14.01
				Acrylic Resin	non-disclosure	0.00693	3.73
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00004	0.02
				Talc;not containing fibers like asbestos	14807-96-6	0.00043	0.23
				Aromatic Carbonyl compounds	non-disclosure	0.00039	0.21
				Cyanoguanidine	461-58-5	0.00001	0.01
				Amine compounds	non-disclosure	0.00005	0.03
				Leveling agent and others	non-disclosure	0.00016	0.09
2	Solder Paste	Alloy	0.0293	Sn	7440-31-5	0.02782	95.00
				Sb	7440-36-0	0.00146	5.00
3	Epoxy		0.0121	Di-ester resin	non-disclosure	0.00121	10.00
				Functionalized ester	non-disclosure	0.00121	10.00
				Silver	7440-22-4	0.00966	80.00
4	Passive/Active Components		0.0628	Copper (Cu)	7440-50-8	0.02010	32.00
				Nickel (Ni)	7440-02-0	0.00502	8.00
				Tin (Sn)	7440-31-5	0.00151	2.40
				Ceramic (Ba) Compounds	non-disclosure	0.03617	57.60
5	Active Ics	Silicon	0.0158	Silicon	7440-21-3	0.01584	100.00
6	Wire	Gold	0.0024	Au	7440-57-5	0.00242	99.99
7	Solder Ball	SAC305	0.2451	Sn	7440-31-5	0.23651	96.50
				Ag	7440-57-5	0.00735	3.00
				Cu	7440-50-8	0.00123	0.50
8	Encapsulation	Epoxy Resin	1.0468	Fused Silica	60676-86-0	0.80814	77.20
				Epoxy Resin	non-disclosure	0.09317	8.90
				Phenol Resin	non-disclosure	0.09317	8.90
				Crytalline Silica	14808-60-7	0.03140	3.00
				Carbon Black	1333-86-4	0.00523	0.50
				Metal Hydroxide	non-disclosure	0.01570	1.50
Total Package Weight			1.6003				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts